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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/796,471	03/09/2004	Leilei Zhang	X-1574 US	2282	
²⁴³⁰⁹ XILINX, INC	7590 01/23/2007		EXAMINER		
ATTN: LEGA	AL DEPARTMENT	DIAZ, JOSE R			
2100 LOGIC SAN JOSE, C	= ::		ART UNIT	PAPER NUMBER	
ornivacob, c	21 73124		2815		
			MAIL DATE	DELIVERY MODE	
			01/23/2007	PAPER	

Please find below and/or attached an Office communication concerning this application or proceeding.

Advisory Action Before the Filing of an Appeal Brief

Application No.	Applicant(s)	
10/796,471	ZHANG, LEILEI	
Examiner	Art Unit	
José R. Díaz	2815	

	Examiner	Artonit				
	José R. Díaz	2815				
The MAILING DATE of this communication appe	ears on the cover sheet with the c	orrespondence add	ress			
THE REPLY FILED 18 December 2006 FAILS TO PLACE THIS	S APPLICATION IN CONDITION F	OR ALLOWANCE.				
 The reply was filed after a final rejection, but prior to or or this application, applicant must timely file one of the follow places the application in condition for allowance; (2) a Notal Request for Continued Examination (RCE) in compliant time periods: The period for reply expires 3 months from the mailing date 	wing replies: (1) an amendment, aff otice of Appeal (with appeal fee) in o ce with 37 CFR 1.114. The reply mo e of the final rejection.	idavit, or other evider compliance with 37 C ust be filed within one	nce, which FR 41.31; or (3) of the following			
b) The period for reply expires on: (1) the mailing date of this A no event, however, will the statutory period for reply expire	ater than SIX MONTHS from the mailing	g date of the final rejecti	on.			
Examiner Note: If box 1 is checked, check either box (a) or (b). ONLY CHECK BOX (b) WHEN THE FIRST REPLY WAS FILED WITHIN TWO MONTHS OF THE FINAL REJECTION. See MPEP 706.07(f).						
Extensions of time may be obtained under 37 CFR 1.136(a). The date have been filed is the date for purposes of determining the period of exunder 37 CFR 1.17(a) is calculated from: (1) the expiration date of the set forth in (b) above, if checked. Any reply received by the Office late may reduce any earned patent term adjustment. See 37 CFR 1.704(b NOTICE OF APPEAL	dension and the corresponding amount shortened statutory period for reply orig r than three months after the mailing da	of the fee. The appropr inally set in the final Offi	iate extension fee ce action; or (2) as			
 The Notice of Appeal was filed on A brief in complifing the Notice of Appeal (37 CFR 41.37(a)), or any external a Notice of Appeal has been filed, any reply must be filed AMENDMENTS 	ension thereof (37 CFR 41.37(e)), to	avoid dismissal of th	ns of the date of the appeal. Since			
3. The proposed amendment(s) filed after a final rejection, but prior to the date of filing a brief, will <u>not</u> be entered because (a) They raise new issues that would require further consideration and/or search (see NOTE below); (b) They raise the issue of new matter (see NOTE below);						
(c) They are not deemed to place the application in be appeal; and/or	tter form for appeal by materially re		the issues for			
(d) They present additional claims without canceling a NOTE: (See 37 CFR 1.116 and 41.33(a)).		ected claims.				
4. The amendments are not in compliance with 37 CFR 1.1		empliant Amendment	(PTOL-324).			
5. Applicant's reply has overcome the following rejection(s			·			
6. Newly proposed or amended claim(s) would be a non-allowable claim(s).						
7. For purposes of appeal, the proposed amendment(s): a) how the new or amended claims would be rejected is pro The status of the claim(s) is (or will be) as follows: Claim(s) allowed: Claim(s) objected to:		II be entered and an o	explanation of			
Claim(s) rejected: <u>1-21,31 and 32</u> . Claim(s) withdrawn from consideration: <u>22-30</u> .						
AFFIDAVIT OR OTHER EVIDENCE						
8. The affidavit or other evidence filed after a final action, be because applicant failed to provide a showing of good ar was not earlier presented. See 37 CFR 1.116(e).	nd sufficient reasons why the affidat	vit or other evidence i	s necessary and			
9. The affidavit or other evidence filed after the date of filing entered because the affidavit or other evidence failed to showing a good and sufficient reasons why it is necessary.	overcome <u>all</u> rejections under appe ry and was not earlier presented. S	al and/or appellant fa see 37 CFR 41.33(d)(ils to provide a 1).			
10. ☐ The affidavit or other evidence is entered. An explanation REQUEST FOR RECONSIDERATION/OTHER						
11. The request for reconsideration has been considered by		1	nce because:			
 12. Note the attached Information Disclosure Statement(s). 13. Other: Note the attached figure 2A. 	(PTO/SB/08) Paper No(s). 12/18/	los				
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Continuation Sheet (PTO-303)

Application No.

First, it is noted that the Statement of the Substance of the Informal Interview ("Statement"), as filed on December 18, 2006, is not accurate. In the Statement, applicant states that "[T]he Examiner suggested adding a section line to Fig. 2B and...indicating that the space around the chip capacitors in Fig. 2A is not filled with encapsulant." However, the examiner did not make those suggestions. In fact, Applicant was the one that suggested those amendments in response to the issues raised by the examiner. Therefore, the Statement should be corrected.

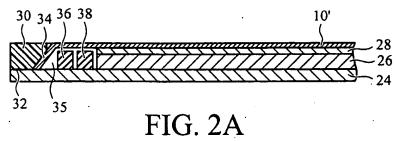
After a carefully review of the original disclosure, it is considered that the proposed amendment add new matter to the specification. For instance, the original disclosure does not support the subject matter now added to paragraph 0030 since the original disclosure fails to suggest, explicitly or implicitly, that no molding compound is introduced in the space 35, as now proposed by applicant. To the contrary, the original disclosure suggests that molding compound is added in the argued space. For example, paragraph 0030 (of the original specification) discloses that the molding compound is formed on "about 2 mm to about 3 mm of the perimeter of the package substrate 24." Paragraph 0030 further discloses that "[T]he set-back from the edge of the package substrate 24 to the chip capacitors 36, 38 is typically about 2-3 mm." As it is illustrated in the attached figure 2A, a length of about 2-3 mm includes the portion 32 and the space 35. Thus, the molding compound is also present in the space 35.

In addition, the proposed figures are objected since the device shown in figures 2A does not correspond to the device shown in figure 2B. For instance, figure 2A shows a sloped wall completely covered (from top to bottom) with molding compound (30), however figure 2B shows a partially covered sloped wall (34) (see the top portion of the sloped wall that is not covered with molding compound 30). Therefore, the figures remain objected by the examiner.

Finally and with regards to the rejections presented in the Office, the examiner considers that the rejections remain proper since applicant fails to clarify the issues previously raised by the examiner.

JEROME JACKSON PRIMARY EXAMINER





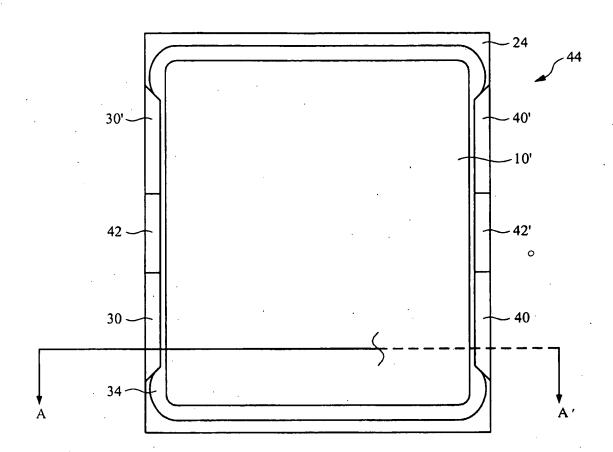


FIG. 2B

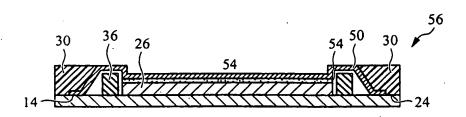


FIG. 2C

Application/Control Number: 10/796,471

Art Unit: 2815

